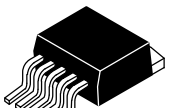
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

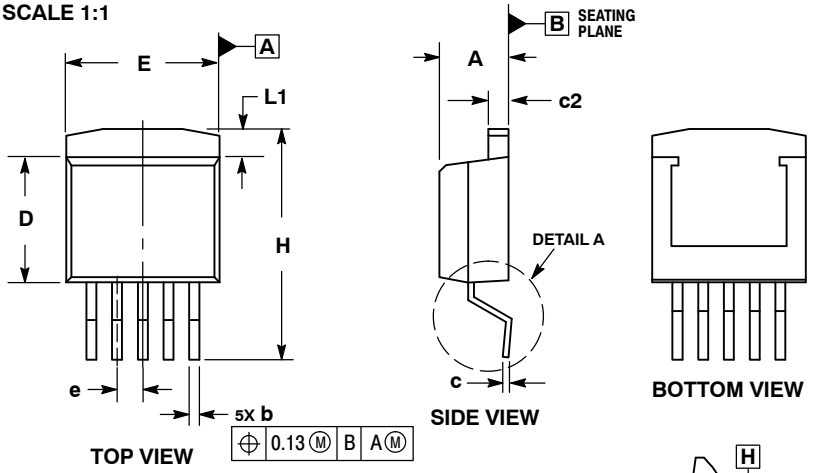
ON Semiconductor®



D²PAK–5 (TO–263, 5 LEAD)
CASE 418AH–01
ISSUE A

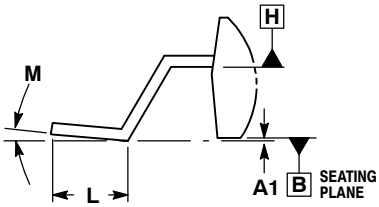
DATE 28 SEP 2010

SCALE 1:1

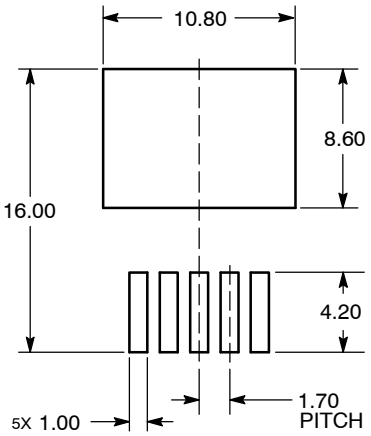


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.13 MAXIMUM PER SIDE. THESE DIMENSIONS TO BE MEASURED AT DATUM H.

	MILLIMETERS	
DIM	MIN	MAX
A	4.06	4.82
A1	0.00	0.25
b	0.51	0.99
c	0.33	0.74
c2	1.14	1.65
D	8.38	9.65
E	9.65	10.67
e	1.70 BSC	
H	14.61	15.88
L	1.78	2.79
L1	---	1.68
M	0 °	8 °



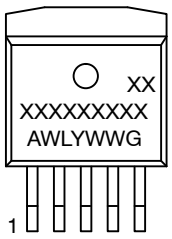
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, “G” or microdot “ ▪”, may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD		
NEW STANDARD:			
DESCRIPTION:	D²PAK–5 (TO–263, 5 LEAD)		PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY D. TRUHITTE.	27 JUL 2010
A	CORRECTED LEAD FOOT DRAWING TO SHOW LEADS BENT UP FROM SEATING PLANE. REQ. BY D. TRUHITTE.	28 SEP 2010